HOSTAFORM® C 9021 ECO-C 872

HOSTAFORM®

Chemical abbreviation according to ISO 1043-1: POM Molding compound ISO 29988- POM-K, M-GNR, 03-002
POM copolymer injection molding type with high rigidity, hardness and toughness; good chemical resistance to solvents, fuel and strong alkalis as well as good hydrolysis resistance; high resistance to thermal and oxidative degradation. Monomers and additives are listed in EU-Regulation (EU) 10/2011 FDA compliant according to 21 CFR 177.2470 .Burning rate ISO 3795 and FMVSS 302 < 75 mm/min for a thickness more than 1 mm. Ranges of applications: automotive engineering, precision engineering, electric and electronical industry, domestic appliances. FDA = Food and Drug Administration (USA) FMVSS = Federal Motor Vehicle Safety Standard (USA) UL = Underwriters Laboratories (USA).
ECO-C: Hostaform® C 9021 ECO-C 872 incorporates circular content derived from captured carbon dioxide emissions in the finished product through mass balance allocation. The product is a drop-in replacement to the standard grade with the same performance and processing properties and contributes to the displacement of virgin fossil fuel resources. The feedstock utilizing captured carbon dioxide emissions is ISCC CFC certified as low carbon intensity methanol.

Product information

Resin Identification	POM	ISO 1043
Part Marking Code	>POM<	ISO 11469

Rheological properties

Melt volume-flow rate	8	cm^3/10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	
Moulding shrinkage, parallel	2.0	%	ISO 294-4, 2577
Moulding shrinkage, normal	1.9[1]	%	ISO 294-4, 2577

[1]: @ 195°C

Typical mechanical properties

Tensile modulus	2850	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	64	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	9	%	ISO 527-1/-2
Nominal strain at break	30	%	ISO 527-1/-2
Flexural modulus	2700	MPa	ISO 178
Flexural strength	89	MPa	ISO 178
Flexural stress at 3.5%	72	MPa	ISO 178
Compressive stress at 1% strain	24	MPa	ISO 604
Tensile creep modulus, 1h	2500	MPa	ISO 899-1
Tensile creep modulus, 1000h	1300	MPa	ISO 899-1
Charpy impact strength, 23°C	220[P]	kJ/m^2	ISO 179/1eU
Charpy impact strength, -30°C	220	kJ/m^2	ISO 179/1eU
Charpy notched impact strength, 23°C	6.5	kJ/m^2	ISO 179/1eA
Charpy notched impact strength, -30°C	6	kJ/m^2	ISO 179/1eA
Ball indentation hardness, H 358/30	144	MPa	ISO 2039-1
Poisson's ratio	0.399		

[P]: Partial Break

HOSTAFORM® C 9021 ECO-C 872

HOSTAFORM®

Thermal properties

Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	104	°C	ISO 75-1/-2
Temperature of deflection under load, 0.45 MPa	160	°C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	110	E-6/K	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	110	E-6/K	ISO 11359-1/-2
Thermal conductivity of melt	0.155	W/(m K)	ISO 22007-2

Flammability

Burning Behav. at 1.5mm nom. thickn.	HB	class	IEC 60695-11-10
Thickness tested	1.5	mm	IEC 60695-11-10
Burning Behav. at thickness h	HB	class	IEC 60695-11-10
Thickness tested	3	mm	IEC 60695-11-10
UL recognition	yes		UL 94

Electrical properties

Relative permittivity, 100Hz	4		IEC 62631-2-1
Relative permittivity, 1MHz	4		IEC 62631-2-1
Dissipation factor, 100Hz	20	E-4	IEC 62631-2-1
Dissipation factor, 1MHz	50	E-4	IEC 62631-2-1
Volume resistivity	1E12	Ohm.m	IEC 62631-3-1
Surface resistivity	1E14	Ohm	IEC 62631-3-2
Electric strength	35	kV/mm	IEC 60243-1
Comparative tracking index	600		IEC 60112
Relative permittivity, printed circuits and boards, 2.5 GHz	3		IEC 61189-2-721
Relative permittivity, printed circuits and boards, 10 GHz	3.2		IEC 61189-2-721
Dissipation factor, printed circuits and boards, 2.5 GHz	466	E-4	IEC 61189-2-721
Dissipation factor, printed circuits and boards, 10 GHz	144	E-4	IEC 61189-2-721

Physical/Other properties

Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	0.65	%	Sim. to ISO 62
Density	1410	kg/m³	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	200	°C
Min. melt temperature	190	°C
Max. melt temperature	210	°C

HOSTAFORM® C 9021 ECO-C 872

HOSTAFORM®

Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	100	°C
Min. mould temperature	80	°C
Max. mould temperature	120	°C
Hold pressure range	60 - 120	MPa
Back pressure	4	MPa
Ejection temperature	127	°C

Characteristics

Processing	Injection Moulding, Film Extrusion, Extrusion, Sheet Extrusion, Other Extrusion, Blow Moulding
Delivery form	Pellets
Additives	Release agent
Sustainability	Carbon Capture

Additional information

Injection molding

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard injection moulding machines with three phase (15 to 25 D) plasticating screws will fit.

Postprocessing

Conditioning e.g. moisturizing is not necessary.

Film extrusion

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard extruders with grooved feed zone and short compression screws (minimum 25 D) will fit.

Melt temperature 180-190 °C

Postprocessing

Conditioning e.g. moisturizing is not necessary.

In case of very thick wall thickness profiles after-annealing it is recommended to reduce internal stress.

Annealing temperature 130-140 °C
Annealing time 10 min/mm thickness

Other extrusion

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard extruders with grooved feed zone and short compression screws (minimum 25 D) will fit.

Melt temperature 180-190 °C

Postprocessing

Conditioning e.g. moisturizing is not necessary.

In case of very thick wall thickness profiles after-annealing it is recommended to reduce internal stress.

Annealing temperature 130-140 °C
Annealing time 10 min/mm thickness

HOSTAFORM® C 9021 ECO-C 872

HOSTAFORM®

Sheet extrusion

HOSTAFORM® C 9021 ECO-C 872

HOSTAFORM®

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard extruders with grooved feed zone and short compression screws (minimum 25 D) will fit.

Melt temperature 180-190 °C

Postprocessing

Conditioning e.g. moisturizing is not necessary.

In case of very thick wall thickness profiles after-annealing it is recommended to reduce internal stress.

Annealing temperature 130-140 °C
Annealing time 10 min/mm thickness

Processing Notes

Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

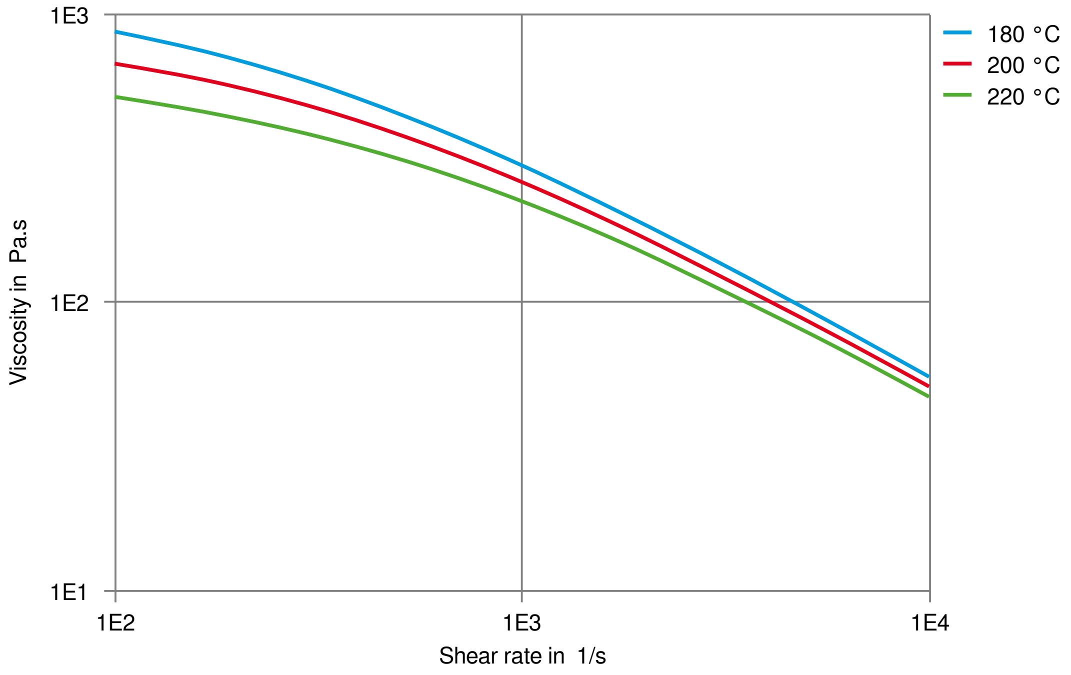
Storage

The product can then be stored in standard conditions until processed.

HOSTAFORM® C 9021 ECO-C 872

HOSTAFORM®

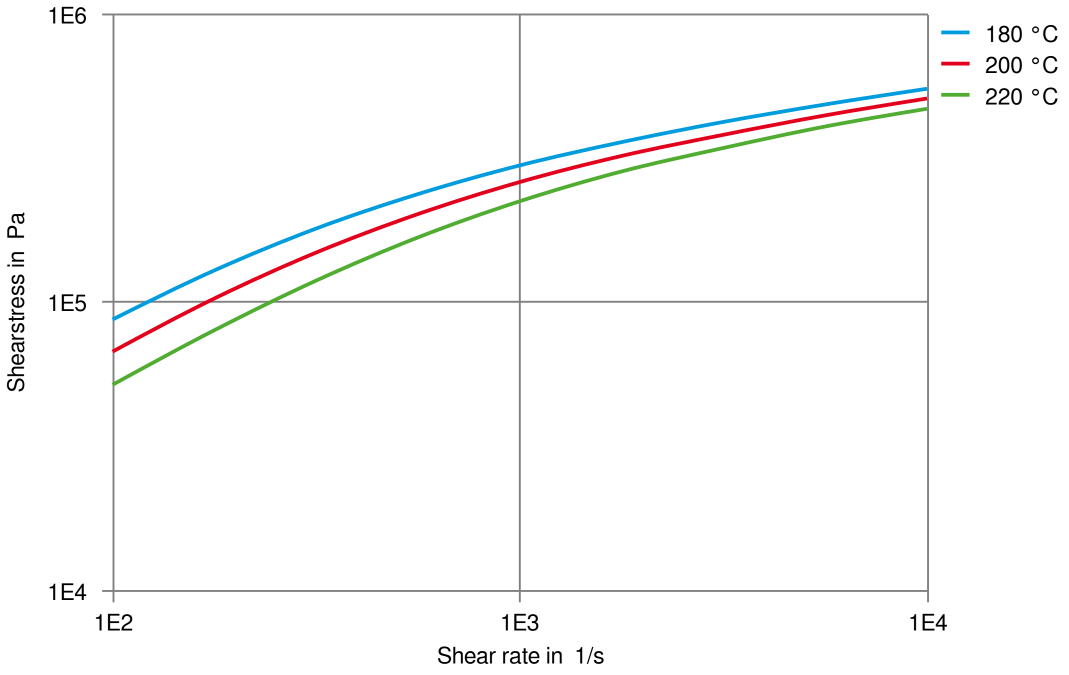
Viscosity-shear rate



HOSTAFORM® C 9021 ECO-C 872

HOSTAFORM®

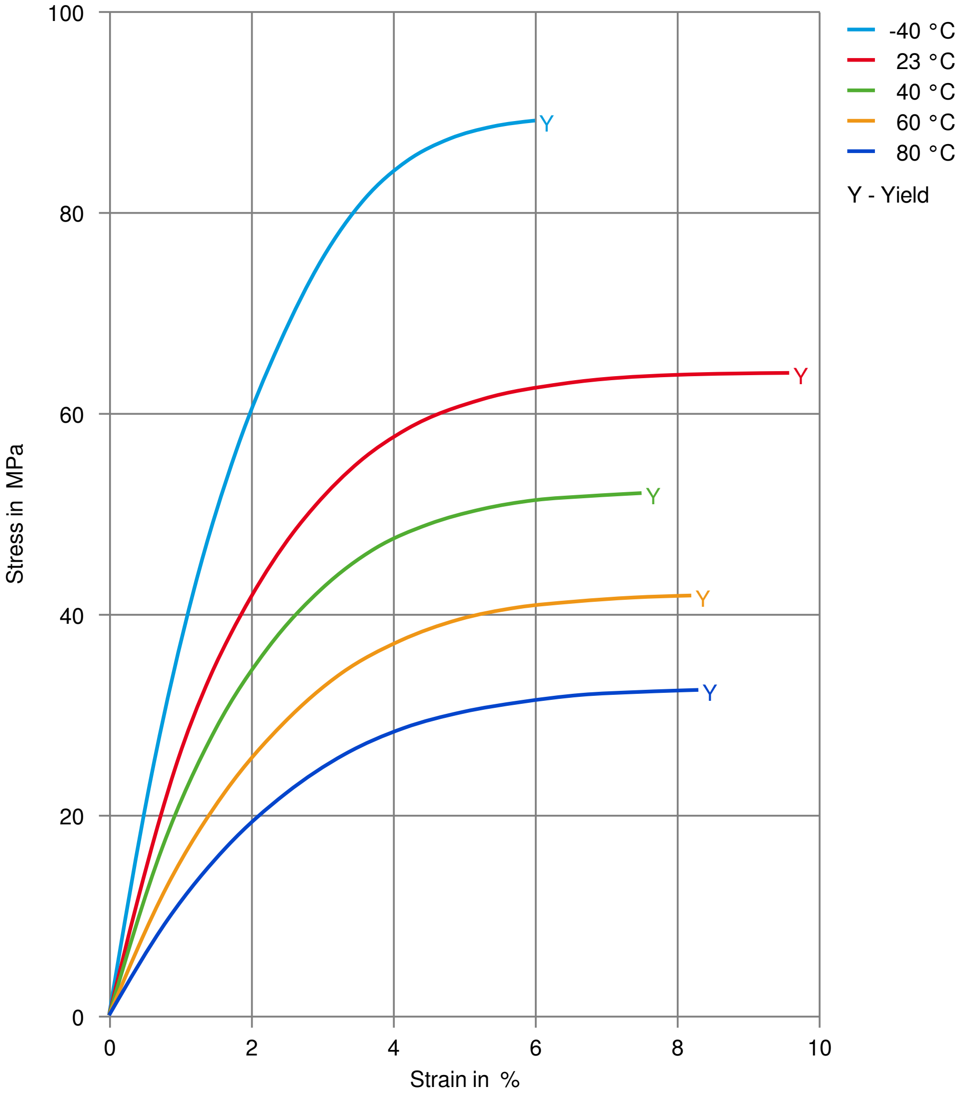
Shearstress-shear rate



HOSTAFORM® C 9021 ECO-C 872

HOSTAFORM®

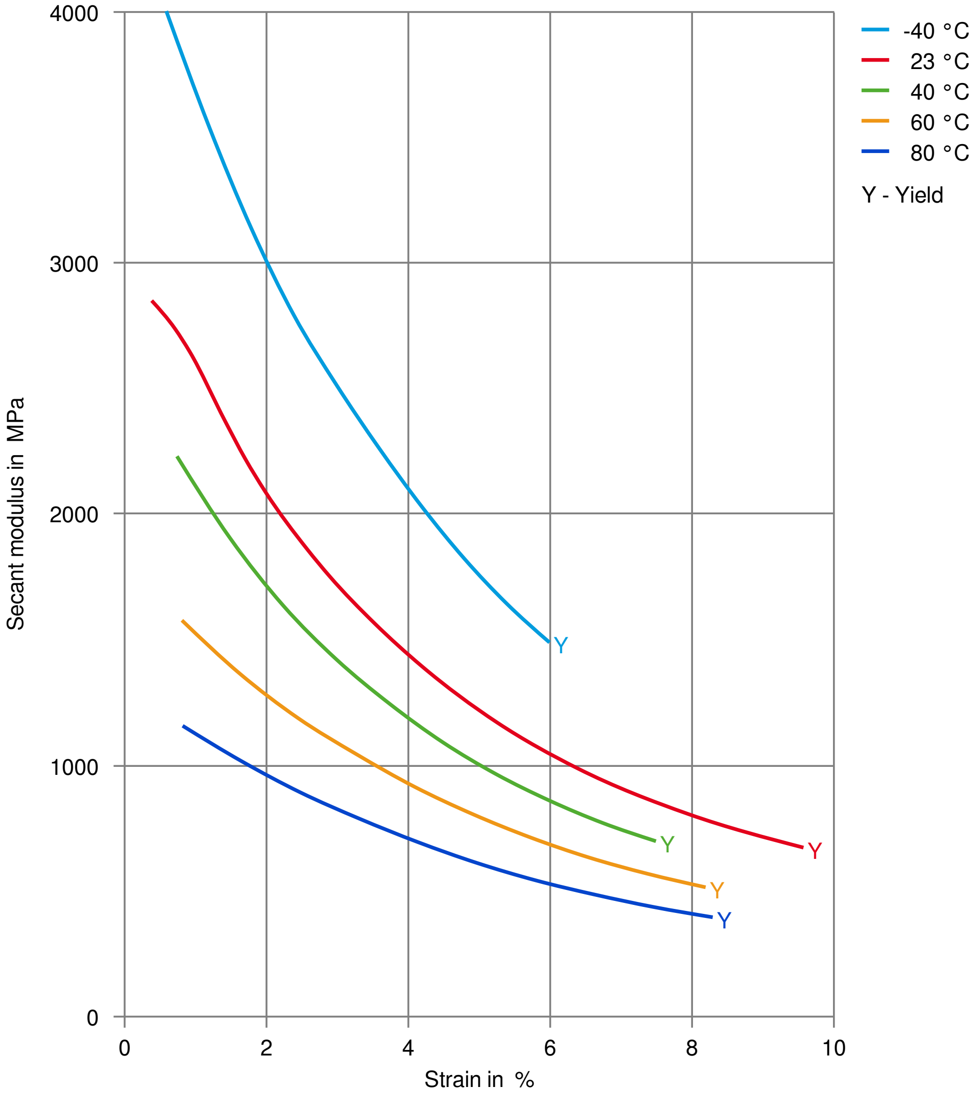
Stress-strain



HOSTAFORM® C 9021 ECO-C 872

HOSTAFORM®

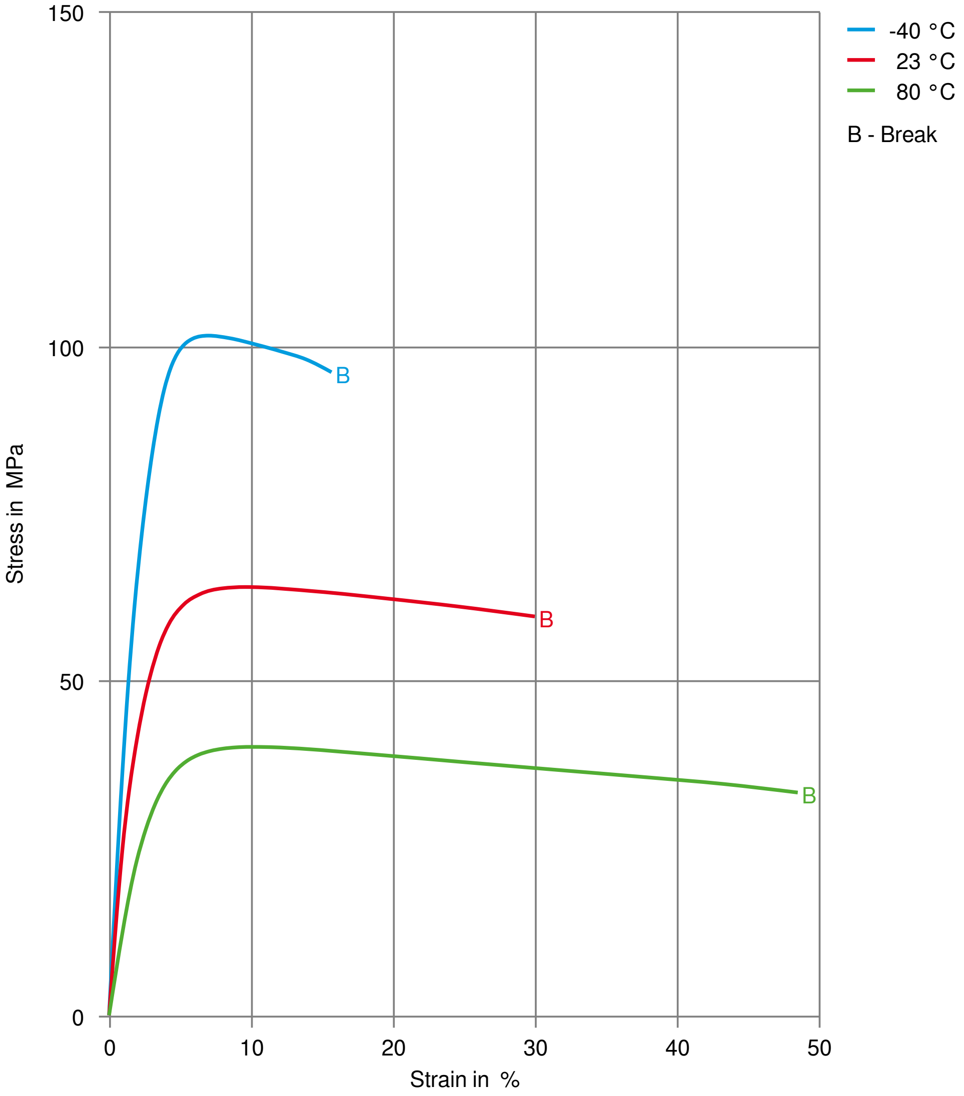
Secant modulus-strain



HOSTAFORM® C 9021 ECO-C 872

HOSTAFORM®

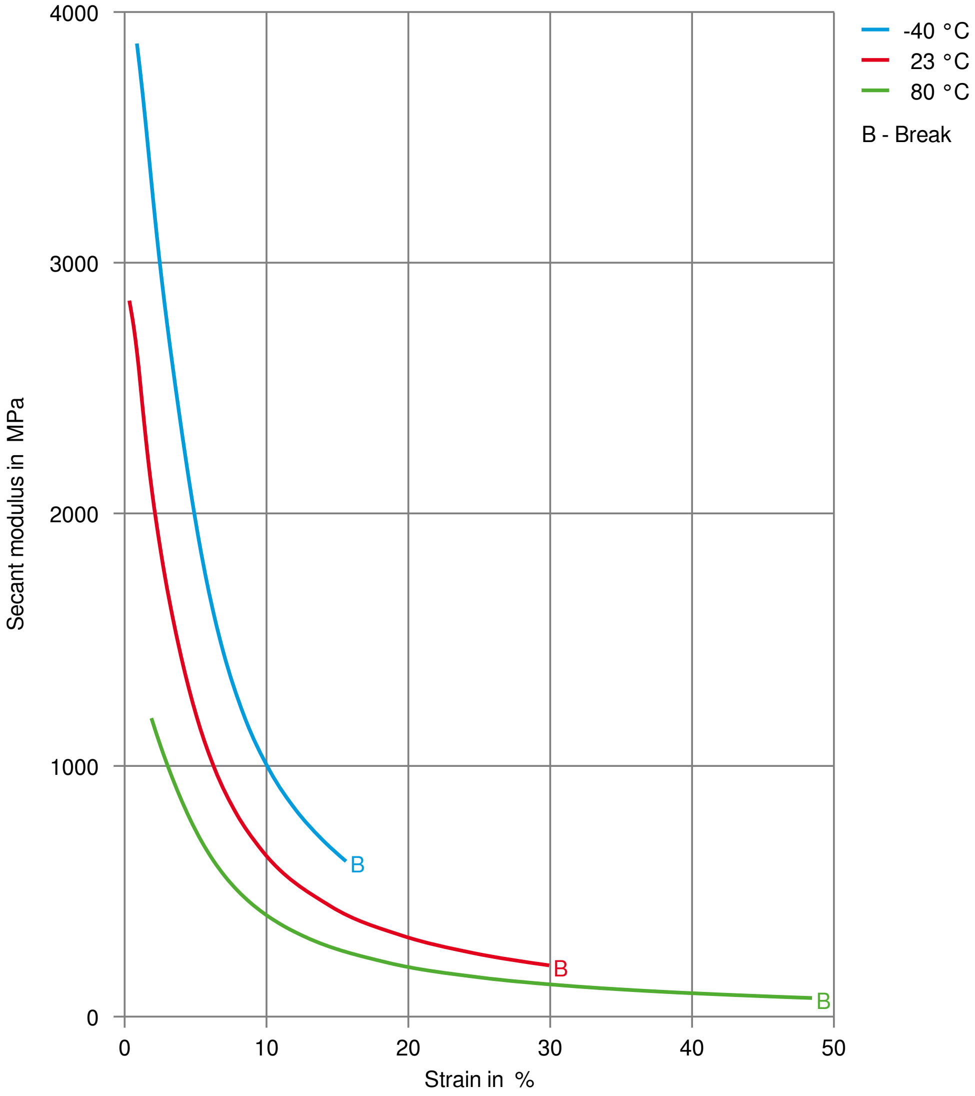
Stress-strain, 50mm/min



HOSTAFORM® C 9021 ECO-C 872

HOSTAFORM®

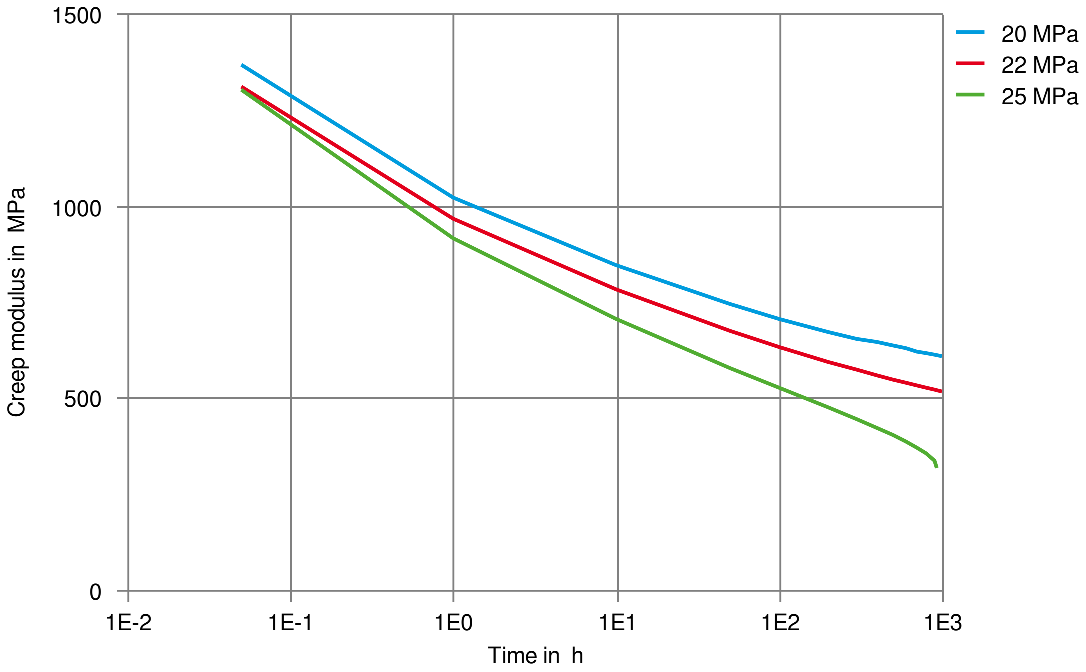
Secant modulus-strain, 50mm/min



HOSTAFORM® C 9021 ECO-C 872

HOSTAFORM®

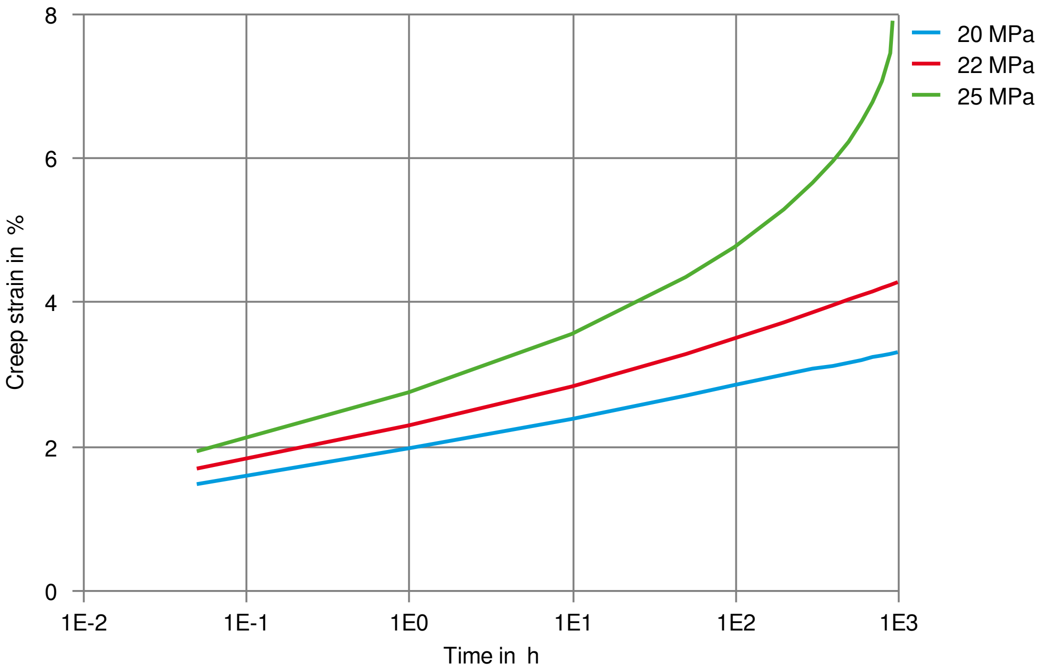
Creep modulus-time 60 °C



HOSTAFORM® C 9021 ECO-C 872

HOSTAFORM®

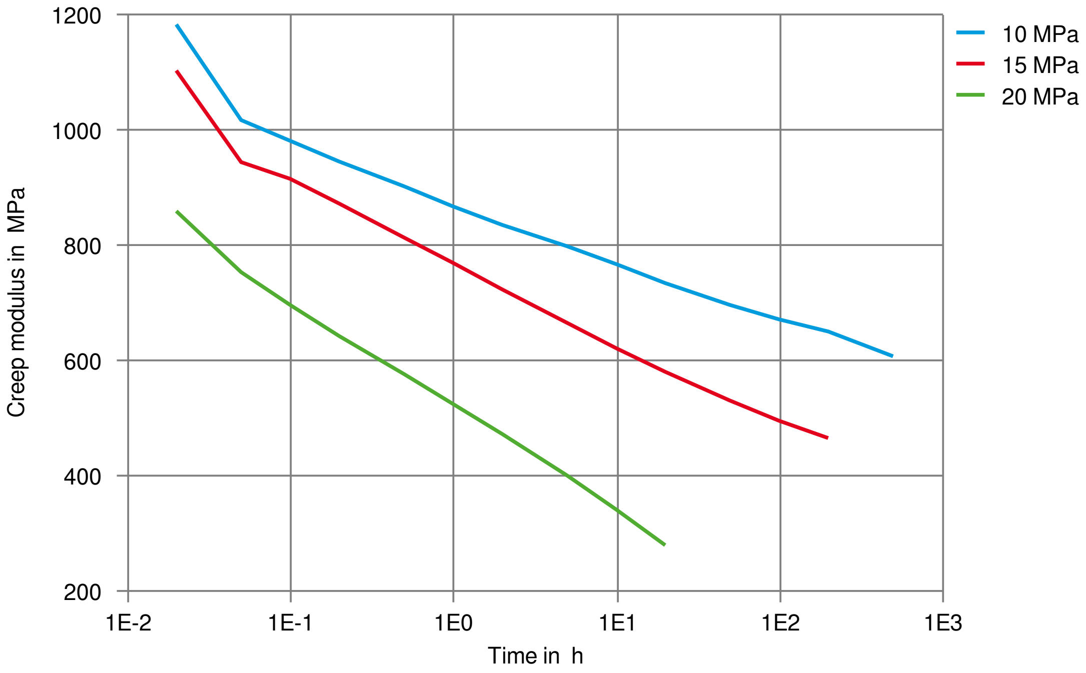
Creep strain-time 60 °C



HOSTAFORM® C 9021 ECO-C 872

HOSTAFORM®

Creep modulus-time 90 °C

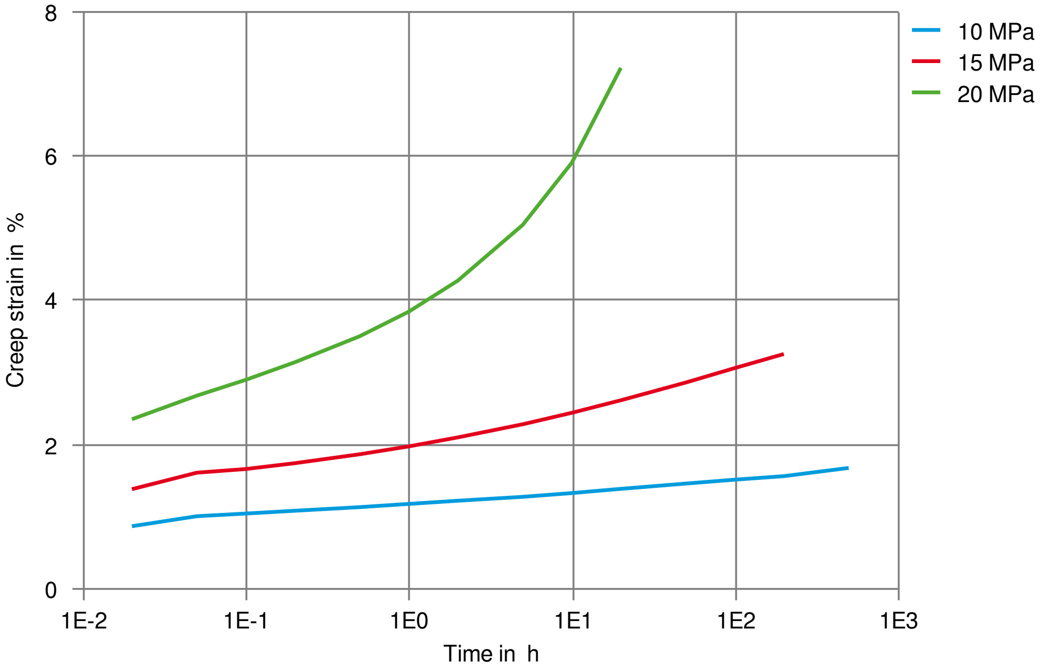


(+) 18816996168
Ponciplastics.com

HOSTAFORM® C 9021 ECO-C 872

HOSTAFORM®

Creep strain-time 90 °C



Revised: 2024-11-27 Source: Celanese Materials Database

NOTICE TO USERS: Values shown are based on testing of laboratory test specimens and represent data that fall within the standard range of properties for natural material. These values alone do not represent a sufficient basis for any part design and are not intended for use in establishing maximum, minimum, or ranges of values for specification purposes. Colourants or other additives may cause significant variations in data values. Properties of moulded parts can be influenced by a wide variety of factors including, but not limited to, material selection, additives, part design, processing conditions and environmental exposure. Other than those products expressly identified as medical grade (including by MT® product designation or otherwise), Celanese's products are not intended for use in medical or dental implants. Regardless of any such product designation, any determination of the suitability of a particular material and part design for any use contemplated by the users and the manner of such use is the sole responsibility of the users, who must assure themselves that the material as subsequently processed meets the needs of their particular product or use. To the best of our knowledge, the information contained in this publication is accurate; however, we do not assume any liability whatsoever for the accuracy and completeness of such information. The information contained in this publication should not be construed as a promise or guarantee of specific properties of our products. It is the sole responsibility of the users to investigate whether any existing patents are infringed by the use of the materials mentioned in this publication. Moreover, there is a need to reduce human exposure to many materials to the lowest practical limits in view of possible adverse effects. To the extent that any hazards may have been mentioned in this publication, we neither suggest nor guarantee that such hazards are the only ones that exist. We recommend that persons intending to rely on any recommendation or to use any equipment, processing technique or material mentioned in this publication should satisfy themselves that they can meet all applicable safety and health standards. We strongly recommend that users seek and adhere to the manufacturer's current instructions for handling each material they use, and entrust the handling of such material to adequately trained personnel only. Please call the telephone numbers listed for additional technical information. Call Customer Services for the appropriate Materials Safety Data Sheets (MSDS) before attempting to process our products.
© 2025 Celanese or its affiliates. All rights reserved. Celanese®, registered C-ball design and all other trademarks identified herein with ®, TM, SM, unless otherwise noted, are trademarks of Celanese or its affiliates. Fortron is a registered trademark of Fortron Industries LLC.